JET PROPULSION LABORATORY

INTEROFFICE MEMORANDUM

TES DFM #977-4.1.1 10/13/00

TO: Design File

FROM: Ed Miller

SUBJECT: RAD6K Flight Computer HRCR Completion

REF: TES Design File Memo #937-4.2.1

The HRCR for the TES C&DH RAD6K Flight Computer Assembly, ref. des. 2045FC01, was completed on 07/13/2000.

All action items generated at that review have now been closed.

A copy of the completed and signed HRCR form is attached, and is included with the End Item Data Package (EIDP). A hard copy of the EIDP may be found in the TES project files, in the I&T files, and in the JPL Vellum Files.

Electronic copies of all TES EIDP's are being made by optically scanning the packages. These electronic copies will be stored on compact disks which will be available from the TES project office upon completion of the scanning.

cc: TES Design File

TES Hardware Requirements Certification Review

Assembly/Subsystem			Co	gniz	zan	t Engineer	Phone	Section			Date		
TES C& DH/Flight Computer				ck V	۷o	oddell	393-3914	3	344		07/13/2000		
Ref. Des.	Drawing No.	Dwg. Rev.	Serial No.			Nomenclature		Fina	Final IR Op. Time Cycles (Mass (Kg)	
2045FC 01	180A432	С	FLT031			Module, Assembly MSP Flight Computer		900759 1947 Min 57 cycles			1.16Kg		
Check applicable answer and give necessary explanation in remarks column			Y 0 5	N 0	N / A	F	Data Attachments			Signature Approval & Date			
Are all drawings and specifications complete, approved, released and frozen?			8	0	0				18. Latest Top Assembly Drawings			Cagnizant Eriginaer	
Do the released drawings and specifications reflect all approved changes?			83		В				S Attached			Contrati PEM	
3. Is hardware identical to other hardware delivered? If no, provide difference list.			0	0	8	Flight spare not deliv	20. Walvers			Materials Engineer			
4 Does the hardware meet the requirement of its FRs, specifications, waivers and/or ICDs ? If no, provide difference list. (See Item 28 for reference.)			8	0	0	Waiver 500045 appro				Charles lemb			
5. Have all discrepancies and MRBs been dispositioned and agreed to by Engineering/ QA?			8	0	0		22. Open Problem Logs & P/FRs Attached Si None			Mas br As	DUSON		
6. Has complete as-built list information been submitted to PDMG?			8	0	0	In vendor's End Item	23. Open Problem Logs & P/FRs on sim. H/W and/or related S/W			System Engineer			
7. Are required design analyses complete, up to date, approved and archived? Attach Identifying list per item 29.			8	0	0	In EIDP & Waiver 500045		☐ Attached ☑None 24. Signed Environmental Test Authorization & Summary (ETAS) ☐ Attached ☑None		Interestion & Test Mgr.			
8. Have all required environmental qualification tests & analyses called for in D-13144, Table 5.2 been completed?			8	0	6			25. Ass Sheet		item Power Data	I pratry mant	Manager //	
Is all required assembly and/or subsystem level functional testing completed?			83	0	0			26. Sho	ortage List		Other /	1600	
10. Have applicable telemetry calibration data been submitted to the System Engineer?			0	0	8				☐ Attached ☑ None 27. Operational Constraints/Idiosyncrasies ☐ Attached ☑ None			Other	
11. Have all required single point failure actions been taken?			0	0	8		28. Requirements Verification Matrix (reference item 4) 28. Attached None			Other			
12. Have all required mass data been submitted?			8	0				29. Design analyses completed, approved & archived (per item 7) Attached S None		Other			
13. Have all stress, corrosion & flammable material requirements been met ?			69	0	[1	The state of the s			Other			
14. Have all piece parts, processes and materials been approved by JPL?			53	0	C]					Other		
15. Has hardware been baked out, cleaned and met all contamination control requirements?			0	88	C	Not baked out yet				Other			
16. Are all required shipping containers, shipping procedures, special handling procedures, AHSE and SE			83	0	1)		1			Other		
ready? 17. Is this hardware acceptable for flight?				8	+	Acceptable for Integration Acceptable for flight after	Into Integrated Electronics Module	+			Other		

Recent discovery of EEPROM solder cracks in ROK